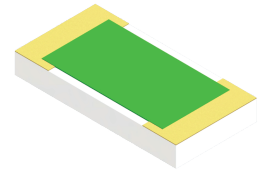


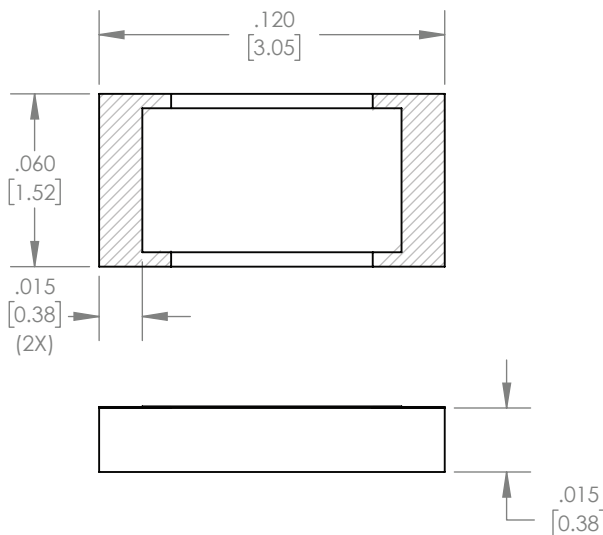
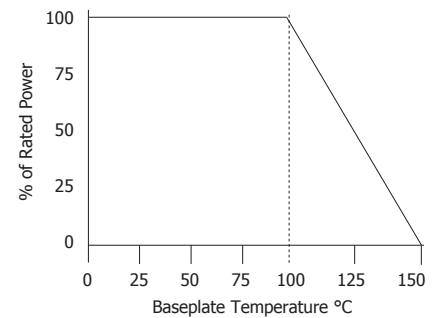
RS1206ZZ-XXXXWN-91 Features:

- Single-Sided (Flip-Chip) Terminal Configuration
- Solder, Epoxy or Wirebondable Terminals
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel (Film Side Down) and Waffle Pack Available (Standard is bulk)


RS1206ZZ-XXXXWN-91 Parameters:

| | |
|------------------------|---|
| Resistance Range: | 0.5Ω - 1MΩ |
| Rated Power*: | 350mW |
| Construction: | Thick Film on 0.015" Al ₂ O ₃ |
| Operating Temperature: | -55 to +150°C |

* Rating based on ≤100°C constant baseplate temperature

RS1206ZZ-XXXXWN-91 Dimensions:

**RS1206ZZ-XXXXWN-91
Power Derating Curve**


Dimensions in inches [mm]
Tolerance is ± 0.005 [0.13]
unless otherwise stated

Ordering Information:
Example Part Number: RS1206CT-50R0JN-91

| RS | 1206 | ZZ | - | XXXX | W | N | - | 91 | UU |
|--|------|----|---|---|---|---|-------|---|--|
| Prefix for Resistor w/ Single-Sided Terminals | | | | Value Code | Tolerance | Normal Inspection Contact factory for additional options | | Substrate 91 - 0.015" Al ₂ O ₃ | Packaging Blank - Bulk WP - Waffle Pack TRD - Tape & Reel |
| Size 1206 | | | | 50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ | 1002 - 10KΩ 1003 - 100KΩ 1004 - 1MΩ | F - 1% G - 2% J - 5% | | | |
| Terminal Metallization | | | | RoHS | Magnetic | Solder | Epoxy | Wirebond | |
| AS - Tin Lead over Platinum Palladium Gold | | | | No | No | Yes | No | No | |
| CB - Tin Lead over Nickel over Silver | | | | No | Yes | Yes | No | No | |
| CC - 100% Matte Tin over Copper over Silver | | | | Yes | No | Yes | No | No | |
| CT - 100% Matte Tin over Nickel over Silver | | | | Yes | Yes | Yes | No | No | |
| GA - Gold | | | | Yes | No | No | Yes | Yes | |

Barry Industries reserves the right to change part number and/or process without notification.

RS1206ZZ-XXXXWN-91 Reliability Specifications:

| Parameter: | Test Condition: | Results: |
|--------------------------------|---|--|
| Short Time Overload | Apply 1.1x Rated Power for 5 Seconds. | ≤ 5.0% Resistance Shift |
| Rated Load Life | Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours | ≤ 5.0% Resistance Shift |
| Moisture Resistance | MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C | ≤ 5.0% Resistance Shift |
| Resistance to Soldering Heat | MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1 | ≤ 5.0% Resistance Shift |
| Resistance to Bonding Exposure | MIL-PRF-55342 Para 4.8.8.2 | ≤ 5.0% Resistance Shift |
| Solderability | MIL-PRF-55342 Para 4.8.12 | >95% Covered |
| High Temperature Storage | 125°C ±2°C for 500 Hours | 1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual) |
| Thermal Shock | -65 to +125 30 Minutes Dwell, 5 Cycles | 1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual) |

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